

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIAHUA ZHU	03/18/2020
YIFAN LI	04/01/2020
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16822597
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ATTORNEY DOCKET NUMBER:	UOA.1389.US
NAME OF SUBMITTER:	MARK L. WEBER
SIGNATURE:	/marklweber/
DATE SIGNED:	04/07/2020
Total Attachments: 2	
source=2020-04-07 -- Executed Assignment#page1.tif	
source=2020-04-07 -- Executed Assignment#page2.tif	

Assignment

In Consideration of good and valuable consideration provided to the undersigned by the Assignee, The University of Akron, 302 E. Buchtel Common, Akron, Ohio 44325, the receipt of which is hereby acknowledged, the undersigned by these presents hereby sold, assigned, transferred and set over unto the said Assignee the entire right, title and interest in and to the improvement in:

**METHOD OF OPERATING SCANNING THERMAL MICROSCOPY PROBE FOR QUANTITATIVE
MAPPING OF THERMAL CONDUCTIVITY**

said invention being fully described and/or claimed in the application for Letters Patent of the United States of America (Serial No. 16/822,597, filed 03/18/2020), in and for the United States and all foreign countries and all additional and divisional applications thereof, the same to be held and enjoyed by said Assignee, his successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patents therefore may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

And Said Assignee is Hereby Authorized to make application for and to receive Letters Patent for said invention in any of said countries of its election.

And By This Covenant The Undersigned will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said Assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patent which may be granted therefore in said Assignee, his successors, assigns or other legal representatives and upon the request and at the expense of said Assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of said Letters Patents to be granted therefore, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein without further compensation, but at the expense of said Assignee, his successors, assigns or other legal representatives.

And The Commissioner of Patents is Hereby Authorized and Requested to issue any and all Letters Patents of the United States for said invention, to said Assignee.

Signed and sealed:


Jiahua Zhu

03/18/2020
Date

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And The Commissioner of Patents is Hereby Authorized and Requested to issue any and all Letters Patents of the United States for said invention, to said Assignee.

Signed and sealed:

Yifan Li
Yifan Li

04/01/2020
Date

File: UOA.1389.US